

Advancing Technology for Humanity

EE COMCAS 201

International Conference on Microwaves, Communications, Antennas and Electronic Systems David Intercontinental Hotel ■13-15 November 2017 ■ Tel Aviv, Israel

Call for Papers

COMCAS 2017 continues the tradition of providing an international, multidisciplinary forum for the exchange of ideas, research results, and industry experience in the areas of microwave/RF/mm-wave engineering, communications, antennas, solid state circuits, electronic devices, engineering in medicine, radar, sonar and electronic systems.

The technical program includes invited talks by international experts and contributed papers and will be complemented by a large industrial exhibition.

Papers are solicited in a wide range of topics:

Important Deadlines

Summary Submission:

May 20, 2017

Acceptance Notification:

July 5, 2017

Full Paper Submission:

September 4, 2017

For more information visit:

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Communications and Sensors 5G systems & millimeter wave propagation Cognitive Radio & Spectral Sharing Communications Security First Responder/Military Communications Green Communication Internet of Things

Long Range Low Power Networks Micro/Pico/Femtocell Devices and Systems MIMO Antenna Systems for Communications Modulation & Signal Processing Technologies On-Body and Short Range Communications Radio over Fiber & Optical/Wireless Convergence Sensor Networks and Technologies Software-Defined Radio & Multiple Access

Antennas, Propagation, and Scattering

Space-Time Coding and Systems

Smart Antennas, Beamforming and MIMO Wave Propagation and Channel Modeling Wave Scattering and RCS NanoEM, Plasmonics, and Applications Metamaterials, FSS and EBG EM Field Theory and Numerical Techniques EM Interference & Compatibility, SI Spectrum Management and Monitoring ELF, RF, µWave, mmW and THz Measurements

Signal Processing (SP) and Imaging

Microwave Imaging and Tomography Acoustic/Sonar Imaging and Techniques Radar SP and Imaging, SAR, ATR MIMO SP for Radar Ground and Foliage Penetration Systems Signal Acquisition and Sensor Management DF, Emitter Location, Elint, Array Processing Target Detection, Identification and Tracking Data Fusion

Time Domain and UWB SP

RF/MW Devices and Circuits, RFICs

Solid-State Devices, RFICs µWave, mmW and Sub-mmW Circuits/Technologies Nano and THz Devices/Technologies Microwave Photonics Passive Components and Circuits Filters and Multiplexers Ferroelectrics, RF MEMS, MOEMS, and NEMS Active Devices and Circuits RF Power Amplifiers and Devices Tunable and Reconfigurable Circuits/Systems Analog/Digital/Mixed RF Circuits Circuit Theory, Modeling and Applications Interconnects, Packaging and MCM CAD Techniques for Devices and Circuits **Emerging Technologies** Thermal Management for Devices

Microwave Systems, Radar, Acoustics

Aeronautical and Space Applications RFID Devices/Systems/Applications Automotive/Transportation Radar & Communications Environmentally Sensitive ("Green") Design UWB and Multispectral Technologies & Systems **Emerging System Architectures** Modelling Techniques for RF Systems Radar Techniques, Systems and Applications Sonar Systems and Applications Wireless Power Transfer & Energy Harvesting Terahertz Systems

Biomedical Engineering

Advances in MRI: Technology, Systems and Applications Medical RF, MW & MMW Applications and Devices Medical Imaging and Image Processing

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All submitted papers will be peer reviewed. Accepted papers will be published in the COMCAS 2017 Proceedings, which will be submitted for inclusion to IEEE Xplore®. For author's instructions and further information, see www.comcas.org.















